12/10/8-Bit, 1 MSPS, 16/12/8/4-Channel, Single-Ended, MicroPower, Serial Interface ADCs

FEATURES

- 1-MHz Sample Rate Serial Devices
- Product Family of 12/10/8-Bit Resolution
- Zero Latency
- 20-MHz Serial Interface
- Analog Supply Range: 2.7 to 5.25V
- I/O Supply Range: 1.7 to 5.25V
- Two SW Selectable Unipolar, Input Ranges: 0 to 2.5V and 0 to 5V
- Auto and Manual Modes for Channel Selection
- 12,8,4-Channel Devices can Share 16 Channel Device Footprint
- Two Programmable Alarm Levels per Channel
- Four Individually Configurable GPIOs
- Typical Power Dissipation: 14.5 mW (+VA = 5V, +VBD = 3V) at 1 MSPS
- Power-Down Current (1 μA)
- Input Bandwidth (47 at 3dB)
- 30-Pin and 38-Pin TSSOP Packages

APPLICATIONS

- PLC / IPC
- Battery Powered Systems
- Medical Instrumentation
- Digital Power Supplies
- Touch Screen Controllers
- High-Speed Data Acquisition Systems
- High-Speed Closed-Loop Systems

DESCRIPTION

The ADS79XX is a 12/10/8-bit multichannel analog-to-digital converter family. The following table shows all twelve devices from this product family.

The devices include a capacitor based SAR A/D converter with inherent sample and hold.

The devices accept a wide analog supply range from 2.7V to 5.25V. Very low power consumption makes these devices suitable for battery-powered and isolated power supply applications.

A wide 1.7V to 5.25V I/O supply range facilitates a glue-less interface with the most commonly used CMOS digital hosts.

The serial interface is controlled by \overline{CS} and SCLK for easy connection with microprocessors and DSP.

The input signal is sampled with the falling edge of \overline{CS} . It uses SCLK for conversion, serial data output, and reading serial data in. The devices allow auto sequencing of preselected channels or manual selection of a channel for the next conversion cycle.

There are two software selectable input ranges (0V - 2.5V and 0V - 5V), four individually configurable GPIOs, and two programmable alarm thresholds per channel. These features make the devices suitable for most data acquisition applications.

The devices offer an attractive power-down feature. This is extremely useful for power saving when the device is operated at lower conversion speeds.

The 16/12-channel devices from this family are available in a 38-pin TSSOP package and the 4/8-channel devices are available in a 30-pin TSSOP package.

NUMBER OF	RESOLUTION						
CHANNELS	12 BIT	10 BIT	8 BIT				
16	ADS7953	ADS7957	ADS7961				
12	ADS7952	ADS7956	ADS7960				
8	ADS7951	ADS7955	ADS7959				
4	ADS7950	ADS7954	ADS7958				

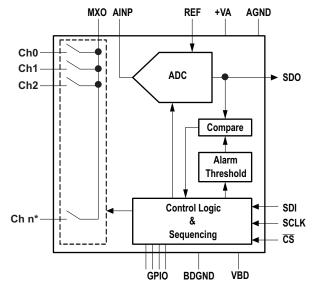
MICROPOWER MULTI-CHANNEL ADS79XX FAMILY



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ADS79XX BLOCK DIAGRAM



NOTE: n* is number of channels (16,12,8, or 4) depending on the device from the ADS79XX product family.

ORDERING INFORMATION - 12-BIT

MODEL	MAXIMUM INTEGRAL LINEARITY (LSB)	MAXIMUM DIFFERENTIAL LINEARITY (LSB)	NO MISSING CODES AT RESOLUTION (BIT)	NUMBER OF CHANNELS	PACKAGE TYPE	PACKAGE DESIGNATOR	TEMPERATURE RANGE	ORDERING INFORMATION	TRANSPORT MEDIA QTY
ADS7953 SB				16	38 pin TSSOP			ADS7953SBDBT	Tube, 50
AD31933 3D				10	36 pin 1330F			ADS7953SBDBTR	Reel, 2000
ADS7952 SB				12	38 pin TSSOP	DBT	–40°C to 125°C	ADS7952SBDBT	Tube, 50
AD37952 3B	±1	±1	12	12				ADS7952SBDBTR	Reel, 2000
ADS7951 SB	±1		12	8 30	30 pin TSSOP			ADS7951SBDBT	Tube, 60
AD37951 3B								ADS7951SBDBTR	Reel, 2000
ADS7950 SB				4	30 pin TSSOP			ADS7950SBDBT	Tube, 60
AD57950 5B					30 pin 1550P			ADS7950SBDBTR	Reel, 2000
ADS7953 S				16				ADS7953SDBT	Tube, 50
AD57953 5					38 pin TSSOP			ADS7953SDBTR	Reel, 2000
1007050.0				40				ADS7952SDBT	Tube, 50
ADS7952 S	.4.5	±2		12	38 pin TSSOP	DBT	40°C to 425°C	ADS7952SDBTR	Reel, 2000
40070540	±1.5	±2	11	0		DBI	–40°C to 125°C	ADS7951SDBT	Tube, 60
ADS7951S		8 30 pin TSSOF 4 30 pin TSSOF		8	30 pm 1550P			ADS7951SDBTR	Reel, 2000
4007050.0	1							ADS7950SDBT	Tube, 60
ADS7950 S			30 pm 1550P	30 pin TSSOP		ADS7950SDBTR	Reel, 2000		

ORDERING INFORMATION - 10-BIT

MODEL	MAXIMUM INTEGRAL LINEARITY (LSB)	MAXIMUM DIFFERENTIAL LINEARITY (LSB)	NO MISSING CODES AT RESOLUTION (BIT)	NUMBER OF CHANNELS	PACKAGE TYPE	PACKAGE DESIGNATOR	TEMPERATURE RANGE	ORDERING INFORMATION	TRANSPORT MEDIA QTY		
ADS7957 S		16 38 pin TSSOP		16				ADS7957SDBT	Tube, 50		
AD37937 3				ADS7957SDBTR	Reel, 2000						
ADS7956 S					10				ADS7956SDBT	Tube, 50	
AD57950 5			10	12	30 pin 1330P	DBT	-40°C to 125°C	ADS7956SDBTR	Reel, 2000		
AD07055 0	±0.5	±0.5	10	8				ADS7955SDBT	Tube, 60		
ADS7955 S				0	30 pin TSSOP			ADS7955SDBTR	Reel, 2000		
4007054.0	1					ADS7954SDBT	Tube, 60				
ADS7954 S				4	30 pin TSSOP	30 pin TSSOP	30 pin TSSOP			ADS7954SDBTR	Reel, 2000

ORDERING INFORMATION - 8-BIT

MODEL	MAXIMUM INTEGRAL LINEARITY (LSB)	MAXIMUM DIFFERENTIAL LINEARITY (LSB)	NO MISSING CODES AT RESOLUTION (BIT)	NUMBER OF CHANNELS	PACKAGE TYPE	PACKAGE DESIGNATOR	TEMPERATURE RANGE	ORDERING INFORMATION	TRANSPORT MEDIA QTY									
ADS7961 S				16	38 pin TSSOP			ADS7961SDBT	Tube, 50									
AD37901 3				10	38 pin TSSOP	36 pin 1330P	36 pin 1330F			ADS7961SDBTR	Reel, 2000							
ADS7960 S				12				ADS7960SDBT	Tube, 50									
AD57960 5	±0.3	±0.3	8	12		36 pin 1330F	DBT	-40°C to 125°C	ADS7960SDBTR	Reel, 2000								
AD07050.0	±0.3	±0.3	0	0	30 pin TSSOP	DBT	-40°C to 125°C	ADS7959SDBT	Tube, 60									
ADS7959 S				8				ADS7959SDBTR	Reel, 2000									
AD07050 0				4					ADS7958SDBT	Tube, 60								
ADS7958 S				4 3	4	4	4	4	4	4	4	30 pin TSSOP	30 pin TSSOP	30 pin TSSOP			ADS7958SDBTR	Reel, 2000

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

		VALUE	UNIT
AINP or CHn to AGI	ND	-0.3 to +VA +0.3	V
+VA to AGND, +VB	D to BDGND	-0.3 to +7.0	V
Digital input voltage	to BDGND	-0.3 to (7.0)	V
Digital output to BD	GND	-0.3 to (+VA + 0.3)	V
Operating temperature range		-40 to 125	°C
Storage temperature	e range	-65 to 150	°C
Junction temperatur	e (T _J Max)	150	°C
	Power dissipation	(T _J Max–T _A)/θ _{JA}	
TSSOP package	θ _{JA} Thermal impedance	100.6	°C/W
ADS79XX family of specifications	devices are rated for MSL2 260°C per the JSTD-020		

(1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS, ADS7950/51/52/53

+VA = 2.7 V to 5.25 V, +VBD = 1.7 V to 5.25 V, T_A = -40°C to 125°C, f_{sample} = 1 MHz (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
ANALOG INPUT						
Full-scale input span ⁽¹⁾	Range 1	0		Vref	V	
	Range 2	0		2*Vref	v	
	Range 1	-0.20		VREF +0.20	V	
Absolute input range	Range 2	-0.20		2*VREF +0.20	v	
Input capacitance			15		ρF	
Input leakage current	$T_A = 125^{\circ}C$		61		nA	
SYSTEM PERFORMANCE						
Resolution			12		Bits	
	ADS795XSB ⁽²⁾	12				
No missing codes	ADS795XS ⁽²⁾	11			Bits	
	ADS795XSB ⁽²⁾	-1	±0.5	1	(2)	
Integral linearity	ADS795XS ⁽²⁾	-1.5	±0.75	1.5	LSB ⁽³⁾	
	ADS795XSB ⁽²⁾	-1	±0.5	1		
Differential linearity	ADS795XS ⁽²⁾	-2	±0.75	1.5	LSB	
Offset error ⁽⁴⁾		-3.5	±1.1	3.5	LSB	
	Range 1	-2	±0.2	2		
	Range 2		±0.2		LSB	
SAMPLING DYNAMICS						
Conversion time	20 MHz sclk			800	nSec	
Acquisition time		325			nSec	
Maximum throughput rate	20 MHz sclk			1.0	MHz	
Aperture delay			5		nsec	
Step response			150		nsec	
Over voltage recovery			150		nsec	
DYNAMIC CHARACTERISTICS						
Total harmonic distortion ⁽⁵⁾	100 kHz		-82		dB	
Signal-to-noise ratio	100 kHz, ADS795XSB ⁽²⁾	70	71.7		dB	
	100 kHz, ADS795XS ⁽²⁾	70	71.7			
Signal-to-noise + distortion	100 kHz, ADS795XSB ⁽²⁾	69	71.3		dB	
	100 kHz, ADS795XS ⁽²⁾	68	71.3			
Spurious free dynamic range	100 kHz		84		dB	
Small signal bandwidth	At –3 dB		47		MHz	
	Any off-channel with 100kHz, Full-scale input to channel being sampled with DC input (isolation crosstalk).		-95			
Channel-to-channel crosstalk	From previously sampled to channel with 100kHz, Full-scale input to channel being sampled with DC input (memory crosstalk).		-85		dB	
ETERNAL REFERENCE INPUT						
Vref reference voltage at REFP		2.49	2.5	2.51	V	
Reference resistance			100		kΩ	

(1) Ideal input span; does not include gain or offset error.

(2) ADS795X, where X indicates 0, 1, 2, or 3

(3) LSB means Least Significant Bit.

(4) Measured relative to an ideal full-scale input

(5) Calculated on the first nine harmonics of the input frequency.

ELECTRICAL CHARACTERISTICS, ADS7950/51/52/53 (continued)

+VA = 2.7 V to 5.25 V, +VBD = 1.7 V to 5.25 V, T_A = -40°C to 125°C, f_{sample} = 1 MHz (unless otherwise noted)

P	ARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ALARM SETTI	NG					
Higher threshol	d range		0		FFC	Hex
Lower threshold	d range		0		FFC	Hex
DIGITAL INPU	T/OUTPUT					
Logic family		CMOS				
	V _{IH}		0.7*(+VBD)			
	V _{IL}	+VBD = 5 V			0.8	
Logic level	V _{IL}	+VBD = 3 V			0.4 5.25 5.25 3	V
	V _{OH}	At I _{source} = 200 μA	Vdd-0.2			
	V _{OL}	At I _{sink} = 200 μA	0.4			
Data format MS	SB first		MS	B First		
POWER SUPP	LY REQUIREMENTS					
+VA supply volt	tage		2.7	3.3	5.25	V
+VBD supply vo	oltage		1.7	3.3	5.25	V
		At +VA = 2.7 to 3.6 V and 1MHz throughput		1.8		mA
Current automated	(At +VA = 2.7 to 3.6 V static state		1.05		mA
Supply current	(normal mode)	At +VA = 4.7 to 5.25 V and 1 MHz throughput		2.3	3	mA
		At +VA = 4.7 to 5.25 V static state		1.1	3 5.25 3 3 1.5	mA
Power-down sta	ate supply current			1		μA
+VBD supply cu	urrent	+VA = 5.25V, f _s = 1MHz		1		mA
Power-up time					1	μSec
Invalid conversi reset	ions after power up or				1	Number s
TEMPERATUR	ERANGE	· · ·	· ·			
Specified perfor	rmance		-40		125	°C

ELECTRICAL CHARACTERISTICS, ADS7954/55/56/57

+VA = 2.7 V to 5.25 V, +VBD = 1.7 V to 5.25 V, $T_A = -40^{\circ}C$ to 125°C, $f_{sample} = 1$ MHz (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG INPUT					
Full-scale input span ⁽¹⁾	Range 1	0		Vref	V
Full-scale input span ?	Range 2	0		2*Vref	v
Abachta innut range	Range 1	-0.20		VREF +0.20	V
Absolute input range	Range 2	-0.20		2*VREF +0.20	v
Input capacitance			15		ρF
Input leakage current	$T_A = 125^{\circ}C$		61		nA
SYSTEM PERFORMANCE				·	
Resolution			10		Bits
No missing codes		10			Bits
Integral linearity		-0.5	±0.2	0.5	LSB ⁽²⁾
Differential linearity		-0.5	±0.2	0.5	LSB
Offset error ⁽³⁾		-1.5	±0.5	1.5	LSB

(1) Ideal input span; does not include gain or offset error.

(2) LSB means Least Significant Bit.

(3) Measured relative to an ideal full-scale input

ELECTRICAL CHARACTERISTICS, ADS7954/55/56/57 (continued)

+VA = 2.7 V to 5.25 V, +VBD = 1.7 V to 5.25 V, T_A = -40°C to 125°C, f_{sample} = 1 MHz (unless otherwise noted)

PARA	METER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Gain error		Range 1	-1	±0.1	1	LSB
Call crist		Range 2		±0.1		LOD
SAMPLING DYNAI	MICS					
Conversion time		20 MHz SCLK			800	nSec
Acquisition time			325			nSec
Maximum throughp	ut rate	20 MHz SCLK			1.0	MHz
Aperture delay				5		nsec
Step response				150		nsec
Over voltage recover	ery			150		nsec
DYNAMIC CHARA	CTERISTICS					
Total harmonic dist	ortion ⁽⁴⁾	100 kHz		-80		dB
Signal-to-noise ratio)	100 kHz	60			dB
Signal-to-noise + di	stortion	100 kHz	60			
Spurious free dynar	nic range	100 kHz		82		dB
Full power bandwid	-	At –3 dB		47		MHz
·		Any off-channel with 100kHz, Full-scale input to channel being sampled with DC input.		-95		
Channel-to-channel crosstalk		From previously sampled to channel with 100kHz, Full-scale input to channel being sampled with DC input.		-85		dB
ETERNAL REFERE	ENCE INPUT					
Vref reference volta	ge at REFP		2.49	2.5	2.51	V
Reference resistance	ce			100		kΩ
ALARM SETTING						
Higher threshold rai	nge		000		FFC	Hex
Lower threshold ran	ige		000		FFC	Hex
DIGITAL INPUT/OU	JTPUT					
Logic family		CMOS				
<u> </u>	VIH		0.7*(+VBD)			
-	V _{IL}	+VBD = 5 V	, ,		0.8	
Logic level	V _{IL}	+VBD = 3 V			0.4	V
	V _{OH}	At I _{source} = 200 μA	Vdd-0.2			
-	V _{OL}	At $I_{sink} = 200 \mu\text{A}$	0.4			
Data format MSB fi			-	B First		
POWER SUPPLY F						
+VA supply voltage			2.7	3.3	5.25	V
+VBD supply voltage	e		1.7	3.3	5.25	V
	-	At +VA = 2.7 to 3.6 V and 1MHz throughput		1.8	0.20	mA
		At +VA = 2.7 to 3.6 V static state $At +VA = 2.7$ to 3.6 V static state		1.05	1	mA
Supply current (nor	mal mode)	At +VA = 4.7 to 5.25 V and 1 MHz throughput		2.3	3	mA
		At $+VA = 4.7$ to 5.25 V static state		1.1	1.5	mA
Power-down state				1.1	1.0	
Power-down state s +VBD supply currer		1/(4 - 5.25)/(f - 1)/(47)		1		μA mA
	ii.	+VA = 5.25V, f _s = 1MHz		I	4	
Power-up time	offer particular				1	µSec
invalid conversions	after power up or				1	Numbe

ELECTRICAL CHARACTERISTICS, ADS7954/55/56/57 (continued)

+VA = 2.7 V to 5.25 V, +VBD = 1.7 V to 5.25 V, $T_A = -40^{\circ}C$ to 125°C, $f_{sample} = 1$ MHz (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP MAX	UNIT
TEMPERATURE RANGE				
Specified performance		-40	125	°C

ELECTRICAL CHARACTERISTICS, ADS7958/59/60/61

+VA = 2.7 V to 5.25 V, +VBD = 1.7 V to 5.25 V, $T_A = -40^{\circ}C$ to 125°C, $f_{sample} = 1$ MHz (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG INPUT					
Full-scale input span ⁽¹⁾	Range 1	0		Vref	V
Full-scale input span ()	Range 2	0		2*Vref	V
Abaoluto input rongo	Range 1	-0.20		VREF +0.20	V
Absolute input range	Range 2	-0.20		2*VREF +0.20	v
Input capacitance			15		ρF
Input leakage current	$T_A = 125^{\circ}C$		61		nA
SYSTEM PERFORMANCE					
Resolution			8		Bits
No missing codes		8			Bits
Integral linearity		-0.3	±0.1	0.3	LSB ⁽²⁾
Differential linearity		-0.3	±0.1	0.3	LSB
Offset error ⁽³⁾		-0.5	±0.2	0.5	LSB
	Range 1	-0.6	±0.1	0.6	LSB
in error	Range 2		±0.1		LOD
SAMPLING DYNAMICS					
Conversion time	20 MHz SCLK			800	nSec
Acquisition time		325			nSec
Maximum throughput rate	20 MHz SCLK			1.0	MHz
Aperture delay			5		nsec
Step response			150		nsec
Over voltage recovery			150		nsec
DYNAMIC CHARACTERISTICS					
Total harmonic distortion ⁽⁴⁾	100 kHz		-75		dB
Signal-to-noise ratio	100 kHz	49			dB
Signal-to-noise + distortion	100 kHz	49			
Spurious free dynamic range	100 kHz		-78		dB
Full power bandwidth	At –3 dB		47		MHz
	Any off-channel with 100kHz, Full-scale input to channel being sampled with DC input.		-95		
Channel-to-channel crosstalk	From previously sampled to channel with 100kHz, Full-scale input to channel being sampled with DC input.		-85		dB
ETERNAL REFERENCE INPUT					
Vref reference voltage at REFP		2.49	2.5	2.51	V
Reference resistance			100		kΩ

(1) Ideal input span; does not include gain or offset error.

(2) LSB means Least Significant Bit.

(3) Measured relative to an ideal full-scale input

(4) Calculated on the first nine harmonics of the input frequency.

ELECTRICAL CHARACTERISTICS, ADS7958/59/60/61 (continued)

+VA = 2.7 V to 5.25 V, +VBD = 1.7 V to 5.25 V, $T_A = -40^{\circ}C$ to 125°C, $f_{sample} = 1$ MHz (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ALARM SETTI	NG		i.			
Higher threshol	d range		000		FF	Hex
Lower threshold	d range		000		FF	Hex
DIGITAL INPU	T/OUTPUT		ц			
Logic family		CMOS				
	V _{IH}		0.7*(+VBD)			
	V _{IL}	+VBD = 5 V			0.8	
Logic level	V _{IL}	+VBD = 3 V			0.4	V
	V _{OH}	At I _{source} = 200 μA	Vdd-0.2			
	V _{OL}	At I _{sink} = 200 μA	0.4			
Data format			MSI	B First		
POWER SUPP	LY REQUIREMENTS	<u>-</u>	U			
+VA supply volt	age		2.7	3.3	5.25	V
+VBD supply vo	oltage		1.7	3.3	5.25	V
		At +VA = 2.7 to 3.6 V and 1MHz throughput		1.8		mA
Current automated	(At +VA = 2.7 to 3.6 V static state		1.05		mA
Supply current	(normai mode)	At +VA = 4.7 to 5.25 V and 1 MHz throughput		2.3	3	mA
		At +VA = 4.7 to 5.25 V static state		1.1	1.5	mA
Power-down sta	ate supply current			1		μA
+VBD supply cu	urrent	+VA = 5.25V, f _s = 1MHz		1		mA
Power-up time					1	μSec
Invalid conversi reset	ons after power up or				1	Numbers
TEMPERATUR	E RANGE					
Specified perfor	rmance		-40		125	°C

TIMING REQUIREMENTS (see Figure 43, Figure 44, Figure 45, and Figure 46)

All specifications typical at -40°C to 125°C, +VA = 2.7 V to 5.25 V (unless otherwise specified)

	PARAMETER	TEST CONDITIONS ⁽¹⁾⁽²⁾	MIN	TYP	MAX	UNIT	
		+VBD = 1.8 V			16		
t _{conv}	Conversion time	+VBD = 3 V			16	SCLK	
		+VBD = 5 V			16		
		+VBD = 1.8 V	40				
tq	Minimum quiet sampling time needed from bus 3-state to start of next conversion	+VBD = 3 V	40			ns	
		+VBD = 5 V	40				
		+VBD = 1.8 V			38		
t _{d1}	Delay time, \overline{CS} low to first data (DO–15) out	+VBD = 3 V			27	ns	
		+VBD = 5 V			17		
		+VBD = 1.8 V			8		
t _{su1}	Setup time, $\overline{\text{CS}}$ low to first rising edge of SCLK	+VBD = 3 V			6	ns	
		+VBD = 5 V	4				
		+VBD = 1.8 V	35				
t _{d2}	Delay time, SCLK falling to SDO next data bit valid	+VBD = 3 V			27	ns	
		+VBD = 5 V			17		

(1) 1.8V specifications apply from 1.7V to 1.9V, 3V specifications apply from 2.7V to 3.6V, 5V specifications apply from 4.75V to 5.25V.

(2) With 50-pF load

TIMING REQUIREMENTS (see Figure 43, Figure 44, Figure 45, and Figure 46) (continued)

All specifications typical at -40°C to 125°C, +VA = 2.7 V to 5.25 V (unless otherwise specified)

	PARAMETER	TEST CONDITIONS ⁽¹⁾⁽²⁾	MIN	TYP	MAX	UNIT				
		+VBD = 1.8 V	7							
t _{h1}	Hold time, SCLK falling to SDO data bit valid	+VBD = 3 V	5			ns				
		+VBD = 5 V	3							
		+VBD = 1.8 V			26					
t _{d3}	Delay time, 16 th SCLK falling edge to SDO 3-state	+VBD = 3 V			22	ns				
		+VBD = 5 V			13					
		+VBD = 1.8 V			2					
t _{su2}	Setup time, SDI valid to rising edge of SCLK	Setup time, SDI valid to rising edge of SCLK +VBD = 3 V 3								
		+VBD = 5 V			4					
		+VBD = 1.8 V	12							
t _{h2}	Hold time, rising edge of SCLK to SDI valid	+VBD = 3 V	10			ns				
		+VBD = 5 V	6							
		+VBD = 1.8 V	20							
t _{w1}	Pulse duration CS high	+VBD = 3 V	20			ns				
		+VBD = 5 V	20			<u> </u>				
		+VBD = 1.8 V			24					
t _{d4}	Delay time \overline{CS} high to SDO 3-state	+VBD = 3 V			21	ns				
		+VBD = 5 V			12	1				
		+VBD = 1.8 V	20							
t _{wh}	Pulse duration SCLK high	+VBD = 3 V	20			ns				
		+VBD = 5 V	20							
		+VBD = 1.8 V	20							
t _{wl}	Pulse duration SCLK low	+VBD = 3 V	20			ns				
		+VBD = 5 V	20			1				
		+VBD = 1.8 V	20							
	Frequency SCLK	+VBD = 3 V			20	MHz				
		+VBD = 5 V			20					

DEVICE INFORMATION

PIN CONFIGURATION (TOP VIEW)

GPIO2 1 GPIO3 2 REFM 3 REFP 4 +VA 5	U	30 GPIO1 29 GPIO0 28 +VBD 27 BDGND 26 SDO	GPIO2 1 GPIO3 2 REFM 3 REFP 4 +VA 5	U	30 GPIO1 29 GPIO0 28 +VBD 27 BDGND 26 SDO
AGND 6 MXO 7 AINP 8 AINM 9 AGND 10 NC 11 CH3 12 NC 13	ADS7950 ADS7954 ADS7958	25 SDI 26 SDI 29 SCLK 23 CS 22 AGND 21 +VA 20 CH0 19 NC 18 CH1	AGND © MXO 7 AINP ® AINM ® AGND 10 CH7 11 CH6 12 CH5 13	ADS7955 ADS7959	20 SDO 25 SDI 24 SCLK 23 CS 22 AGND 21 +VA 20 CH0 19 CH1 18 CH2
CH2 14		17 NC	CH4 [14		17] CH3

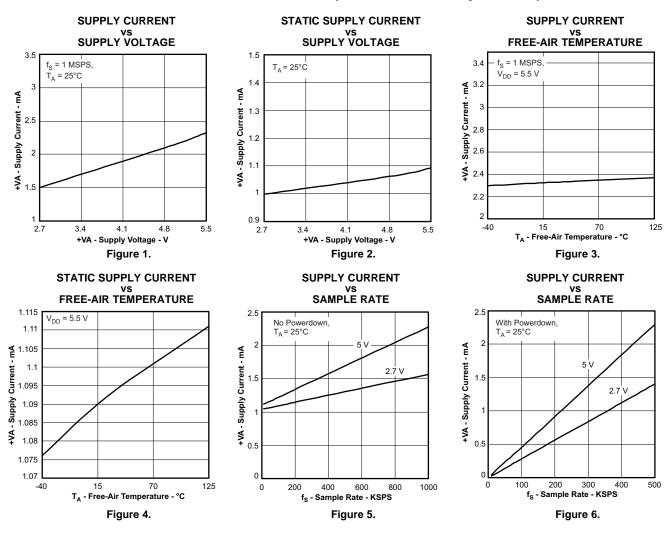
1		1			1
GPIO2 1	U	38 GPIO1	GPIO2 1	U	38 GPIO1
GPIO3 2		37 GPIO0	GPIO3 2		37 GPIO0
REFM 3		36 +VBD	REFM 3		36 +VBD
REFP 4		35 BDGND	REFP 4		35 BDGND
+VA 5		34 SDO	+VA 5		34 SDO
AGND 🖻		33 SDI	AGND 🖻		33 SDI
MXO 7		32 SCLK	MXO 7		32 SCLK
AINP 🛽		31 CS	AINP 🛽		31 CS
AINM ᠑		30 VEE	AINM 🧕		30 VEE
AGND 🄟					29 VCC
NC 1	ADS7956 ADS7960	28 CH0	CH15 11	ADS7957 ADS7961	28 CH0
NC 12		27 CH1	CH14 12		27 CH1
NC 13		26 CH2	CH13 1		261 CH2
NC 14		25 CH3	CH12 🖽		25 CH3
CH11 15		24 CH4	CH11 15		24 CH4
CH10 16		23 CH5	CH10 16		23 CH5
CH9 1		22 CH6	CH9 17		22 CH6
CH8 18		21 CH7	CH8 18		21 CH7
AGND 19		20 AGND	AGND 19		20 AGND
		-			-

TERMINAL FUNCTIONS

DEVICE NAME									
ADS7953 ADS7957 ADS7961	ADS7952 ADS7956 ADS7960	ADS7951 ADS7955 ADS7959	ADS7950 ADS7954 ADS7958	PIN NAME I/O		FUNCTION			
	PIN	NO.							
REFERENCE	E								
4	4	4	4	REFP	I	Reference input			
3	3	3	3	REFM	I	Reference ground			
ADC ANALC	OG INPUT								
8	8	8	8	AINP	I	Signal input to ADC			
9	9	9	9	AINM	I	ADC input ground			
MULTIPLEX	ER								
7	7	7	7	MXO	0	Multiplexer output			
28	28	20	20	Ch0	I	Analog channels for multiplexer			
27	27	19	18	Ch1	I				
26	26	18	14	Ch2	I				
25	25	17	12	Ch3	I				
24	24	14	-	Ch4	I				
23	23	13	-	Ch5	I				
22	22	12	-	Ch6	I				
21	21	11	-	Ch7	I				
18	18	-	-	Ch8	I				
17	17	-	-	Ch9	I				
16	16	-	-	Ch10	I				
15	15	-	-	Ch11	I				
14	-	-	-	Ch12	I				
13	-	-	-	Ch13	I				
12	-	-	-	Ch14	I				
11	-	-	-	Ch15	I				
DIGITAL CO	NTROL SIG	NALS							
31	31	23	23	CS	I	Chip select input			

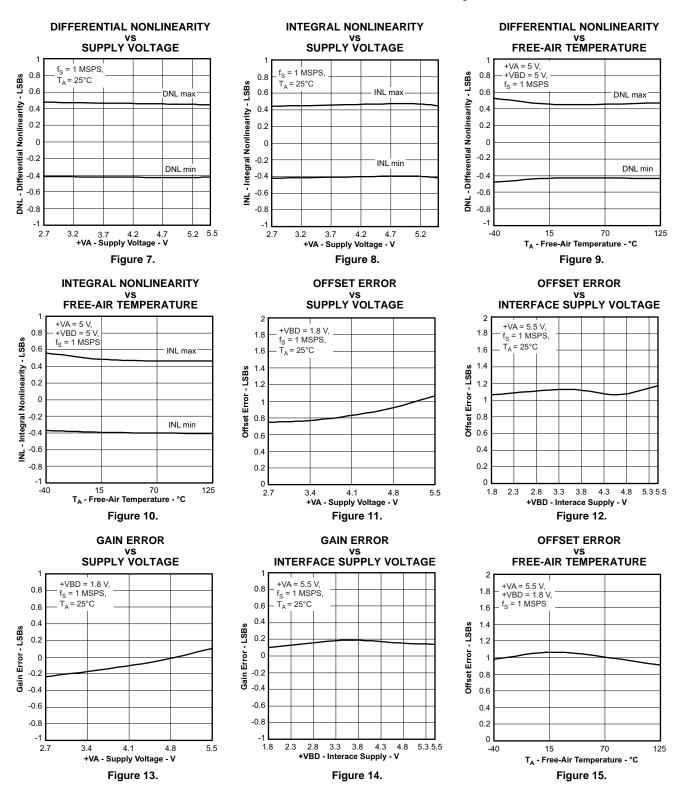
TERMINAL FUNCTIONS (continued)

	DEVICE NAME							
ADS7953 ADS7957 ADS7961	ADS7952 ADS7956 ADS7960	ADS7951 ADS7955 ADS7959	ADS7950 ADS7954 ADS7958	PIN NAME	I/O	FUNCTION		
PIN NO.								
32	32	24	24	SCLK	Ι	Serial clock input		
33	33	25	25	SDI	Ι	Serial data input		
34	34	26	26	SDO	0	Serial data output		
GENERAL P programming		PUTS / OUTP	UTS: These p	ins have prograr	nmable dua	I functionality. Refer to Table 8 for functionality		
37	37	29	29	GPIO0	I/O	General purpose input or output		
				High alarm or High/Low alarm	0	Active high output indicating high alarm or high/low alarm depending on programming		
38	38	30	30	GPIO1	I/O	General purpose input or output		
				Low alarm	0	Active high output indicating low alarm		
1	1	1	1	GPIO2	I/O	General purpose input or output		
				Range	I	Selects range: High -> Range 2 / Low -> Range 1		
2	2	2	2	GPIO3	I/O	General purpose input or output		
				PD	I	Active low power down input		
POWER SUP	PPLY AND G	ROUND						
5, 29	5, 29	5, 21	5, 21	+VA	_	Analog power supply		
6, 10 19, 20, 30	6, 10 19, 20, 30	6, 10, 22	6, 10, 22	AGND	_	Analog ground		
36	36	28	28	+VBD	_	Digital I/O supply		
35	35	27	27	BDGND	_	Digital ground		
NC PINS								
_	11, 12, 13, 14	15, 16	11, 13, 15, 16, 17, 19	—	—	Pins internally not connected, do not float these pins		

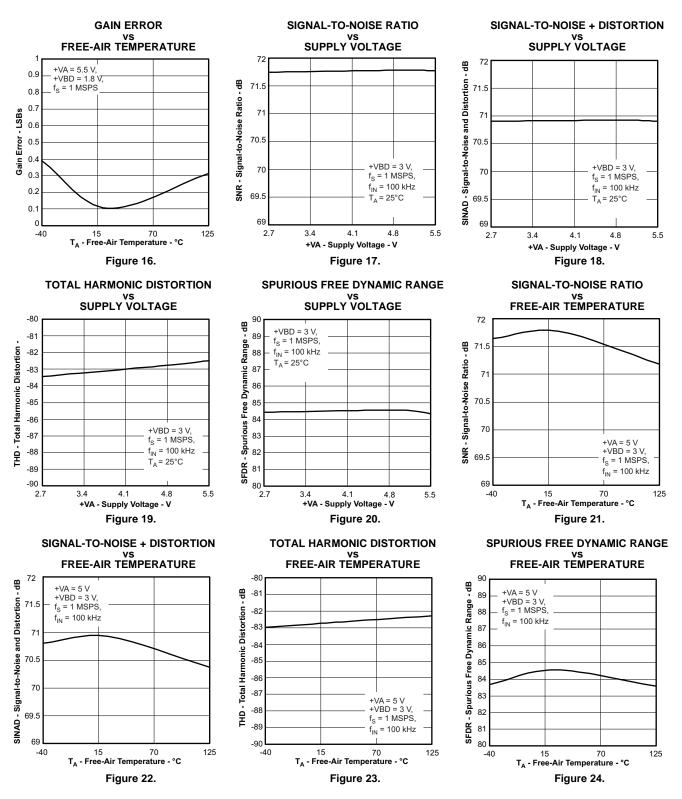


TYPICAL CHARATERISTICS (all ADS79XX Family Devices)

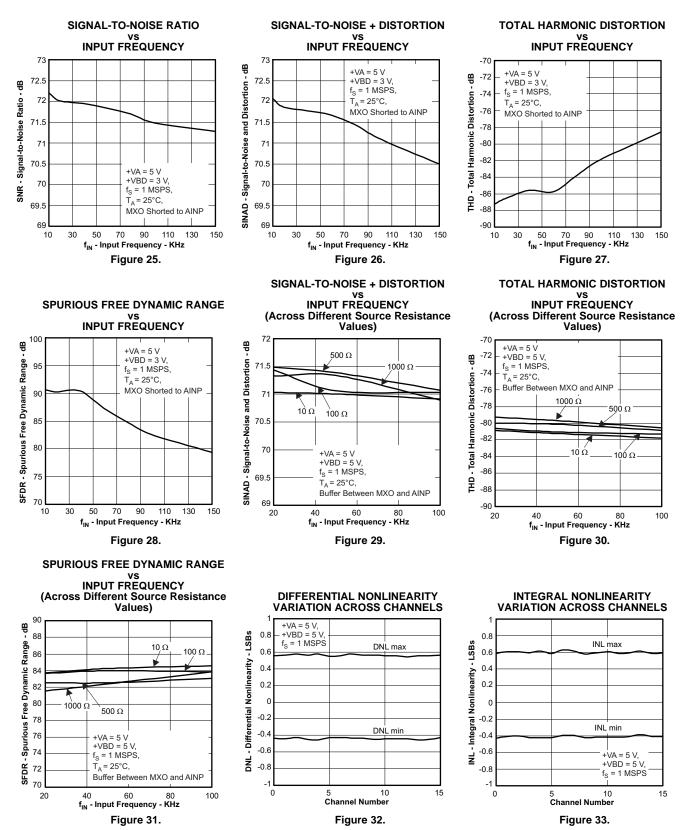
TYPICAL CHARACTERISTICS (12-Bit Devices Only)



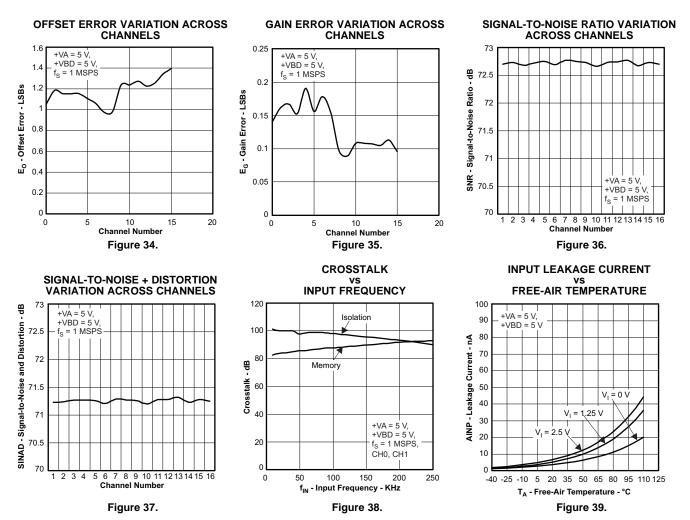
TYPICAL CHARACTERISTICS (12-Bit Devices Only) (continued)



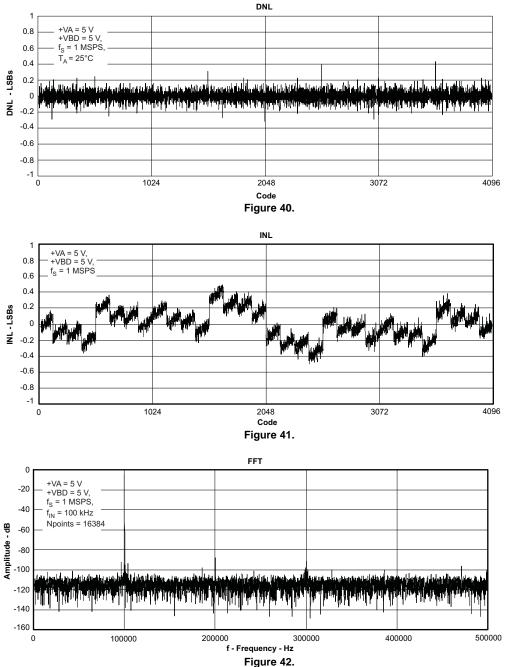
TYPICAL CHARACTERISTICS (12-Bit Devices Only) (continued)



TYPICAL CHARACTERISTICS (12-Bit Devices Only) (continued)



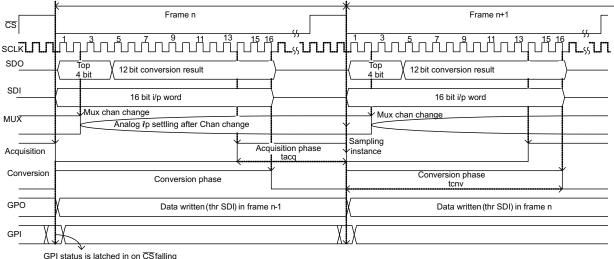
TYPICAL CHARACTERISTICS (12-Bit Devices Only)



DETAILED DESCRIPTION

DEVICE OPERATION

The ADS7950 to ADS7961 are 12/10/8-bit multichannel devices. Figure 43, Figure 44, Figure 45, and Figure 46 show device operation timing. Device operation is controlled with CS, SCLK, and SDI. The device outputs its data on SDO.



edge and transferred to SDO frame n

Figure 43. Device Operation Timing Diagram

Each frame begins with the falling edge of \overline{CS} . With the falling edge of \overline{CS} , the input signal from the selected channel is sampled, and the conversion process is initiated. The device outputs data while the conversion is in progress. The 16-bit data word contains a 4-bit channel address, followed by a 12-bit conversion result in MSB first format. There is an option to read the GPIO status instead of the channel address. (Refer to Table 1, Table 2, and Table 5 for more details.)

The device selects a new multiplexer channel on the second SCLK falling edge. The acquisition phase starts on the fourteenth SCLK rising edge. On the next CS falling edge the acquisition phase will end, and the device starts a new frame.

The device has four *General Purpose IO* (GPIO) pins. These four pins can be individually programmed as GPO or GPI. It is also possible to use them for preassigned functions, refer to Table 10. GPO data can be written into the device through the SDI line. The device refreshes the GPO data on the CS falling edge as per the SDI data written in previous frame.

Similarly the device latches GPI status on the \overline{CS} falling edge and outputs the GPI data on the SDO line (if GPI read is enabled by writing DI04=1 in the previous frame) in the same frame starting with the \overline{CS} falling edge.

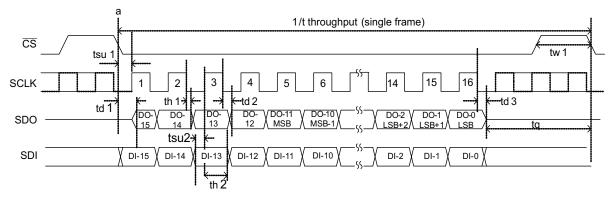


Figure 44. Serial Interface Timing Diagram for 12-Bit Devices (ADS7950/51/52/53)

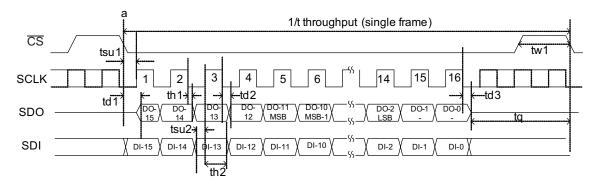


Figure 45. Serial Interface Timing Diagram for 10-Bit Devices (ADS7954/55/56/57)

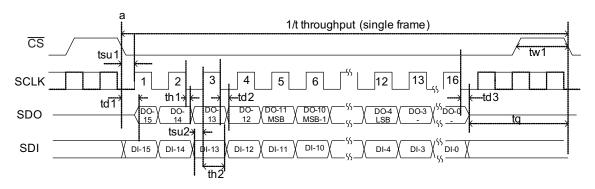


Figure 46. Serial Interface Timing Diagram for 8-Bit Devices (ADS7958/59/60/61)

The falling edge of \overline{CS} clocks out DO-15 (first bit of the four bit channel address), and remaining address bits are clocked out on every falling edge of SCLK until the third falling edge. The conversion result MSB is clocked out on the 4th SCLK falling edge and LSB on the 15th/13th/11th falling edge respectively for 12/10/8-bit devices. On the 16th falling edge of SCLK, SDO goes to the 3-state condition. The conversion ends on the 16th falling edge of SCLK.

The device reads a sixteen bit word on the SDI pin while it outputs the data on the SDO pin. SDI data is latched on every rising edge of SCLK starting with the 1st clock as shown in Figure 44, Figure 45, and Figure 46.

CS can be asserted (pulled high) only after 16 clocks have elapsed.

The device has two (high and low) programmable alarm thresholds per channel. If the input crosses these limits; the device flags out an alarm on GPIO0/GPIO1 depending on the GPIO program register settings (refer to Table 10). The alarm is asserted (under the alarm conditions) on the 12th falling edge of SCLK in the same frame when a data conversion is in progress. The alarm output is reset on the 10th falling edge of SCLK in the next frame.

The device offers a power-down feature to save power when not in use. There are two ways to powerdown the device. It can be powered down by writing DI05 = 1 in the mode control register (refer to Table 1, Table 2, and Table 5); in this case the device powers down on the 16th falling edge of SCLK in the next data frame. Another way to powerdown the device is through GPIO. GPIO3 can act as the PD input (refer to Table 10, to assign this functionality to GPIO3). This is an asynchronous and active low input. The device powers down instantaneously after GPIO3 (PD) = 0. The device will power up again on the CS falling edge with DI05 = 0 in the mode control register and GPIO3 (PD) = 1.

CHANNEL SEQUENCING MODES

There are three modes for channel sequencing, namely *Manual mode*, *Auto-1 mode*, *Auto-2 mode*. Mode selection is done by writing into the *control register* (refer to Table 1, Table 2, and Table 5). A new multiplexer channel is selected on the second falling edge of SCLK (as shown in Figure 43) in all three modes.

Manual mode: When configured to operate in Manual mode, the next channel to be selected is programmed in each frame and the device selects the programmed channel in the next frame. On powerup or after reset the default channel is 'Channel-0' and the device is in Manual mode.

Auto-1 mode: In this mode the device scans pre-programmed channels in ascending order. A new multiplexer channel is selected every frame on the second falling edge of SCLK. There is a separate 'program register' for pre-programming the channel sequence. Table 3 and Table 4 show Auto-1 'program register' settings.

Once programmed the device retains 'program register' settings until the device is powered down, reset, or reprogrammed. It is allowed to exit and re-enter the Auto-1 mode any number of times without disturbing 'program register' settings.

The Auto-1 program register is reset to FFF/FF/FF/F hex for the 16/12/8/4 channel devices respectively upon device powerup or reset; implying the device scans all channels in ascending order.

Auto-2 mode: In this mode the user can configure the program register to select the last channel in the scan sequence. The device scans all channels from channel 0 up to and including the last channel in ascending order. The multiplexer channel is selected every frame on the second falling edge of SCLK. There is a separate 'program register' for pre-programming of the last channel in the sequence (multiplexer depth). Table 6 lists the 'Auto-2 prog' register settings for selection of the last channel in the sequence.

Once programmed the device retains program register settings until the device is powered down, reset, or reprogrammed. It is allowed to exit and re-enter Auto-2 mode any number of times, without disturbing the 'program register' settings.

On powerup or reset the bits D9-D6 of the Auto-2 program register are reset to F/B/7/3 hex for the 16/12/8/4 channel devices respectively; implying the device scans all channels in ascending order.

DEVICE PROGRAMMING AND MODE CONTROL

The following section describes device programming and mode control. These devices feature two types of registers to configure and operate the devices in different modes. These registers are referred as 'Configuration Registers'. There are two types of 'Configuration Registers' namely 'Mode control registers' and 'Program registers'.

Mode Control Register

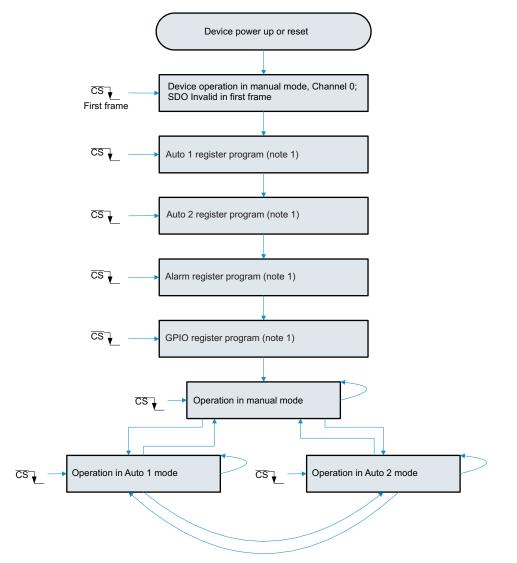
A 'Mode control register' is configured to operate the device in one of three channel sequencing modes, namely Manual mode, Auto-1 Mode, Auto-2 Mode. It is also used to control user programmable features like range selection, device power-down control, GPIO read control, and writing output data into the GPIO.

Program Registers

The 'Program registers' are used for device configuration settings and are typically programmed once on powerup or after device reset. There are different program registers such as 'Auto-1 mode programming' for pre-programming the channel sequence, 'Auto-2 mode programming' for selection of the last channel in the sequence, 'Alarm programming' for all 16 channels (or 12,8,4 channels depending on the device) and GPIO for individual pin configuration as GPI or GPO or a pre-assigned function.

DEVICE POWER-UP SEQUENCE

The device power-up sequence is shown in Figure 47. Manual mode is the default power-up channel sequencing mode and Channel-0 is the first channel by default. As explained previously, these devices offer Program Registers to configure user programmable features like GPIO, Alarm, and to pre-program the channel sequence for Auto modes. At 'powerup or on reset' these registers are set to the default values listed in Table 1 to Table 10. It is recommended to program these registers on powerup or after reset. Once configured; the device is ready to use in any of the three channel sequencing modes namely Manual, Auto-1, and Auto-2.



- (1) The device continues its operation in Manual mode channel 0 through out the programming sequence and outputs valid conversion results. It is possible to change channel, range, GPIO by inserting extra frames in between two programming blocks. It is also possible to bypass any programming block if the user does not intent to use that feature.
- (2) It is possible to reprogram the device at any time during operation, regardless of what mode the device is in. During programming the device continues its operation in whatever mode it is in and outputs valid data.

Figure 47. Device Power-Up Sequence

OPERATING IN MANUAL MODE

The details regarding entering and running in Manual channel sequencing mode are illustrated in Figure 48. Table 1 lists the Mode Control Register settings for Manual mode in detail. Note that there are no Program Registers for manual mode.

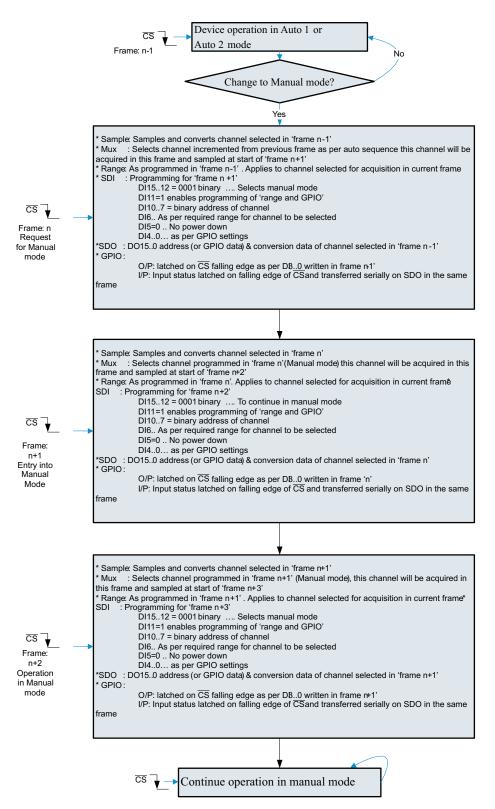


Figure 48. Entering and Running in Manual Channel Sequencing Mode

	DECET			DESCRI	PTION					
BITS	RESET STATE	LOGIC STATE	FUNCTION							
DI15-12	0001	0001	Selects Manual Mod	le						
DI11	0	1	Enables programmir	Enables programming of bits DI06-00.						
		0	Device retains values of DI06-00 from the previous frame.							
DI10-07	0000			address of the next chan channel- 0, 0001 represe		e next frame. DI10: MSB and				
DI06	0	0	Selects 2.5V i/p rang	ge (Range 1)						
		1	Selects 5V i/p range (Range 2)							
DI05 0	0	0	Device normal operation (no powerdown)							
		1	Device powers down on 16th SCLK falling edge							
DI04	0	0	SDO outputs current channel address of the channel on DO1512 followed by 12 bit conversion result on DO1100.							
		1		(both input and output) is 1-DO00 represent 12-bit		O12 in the order shown below.				
			DOI5	DOI4	DOI3	DOI2				
			GPIO3	GPIO2	GPIO1	GPIO0				
DI03-00	0000			gured as output. Device v ng GPIO information is g		he channel which is configured				
			DI03	DI02	DI01	D100				
			GPIO3	GPIO2	GPIO1	GPIO0				

Table 1. Mode Control Register Settings for Manual Mode

OPERATING IN AUTO-1 MODE

The details regarding entering and running in Auto-1 channel sequencing mode are illustrated in the flowchart in Figure 49. Table 2 lists the Mode Control Register settings for Auto-1 mode in detail.

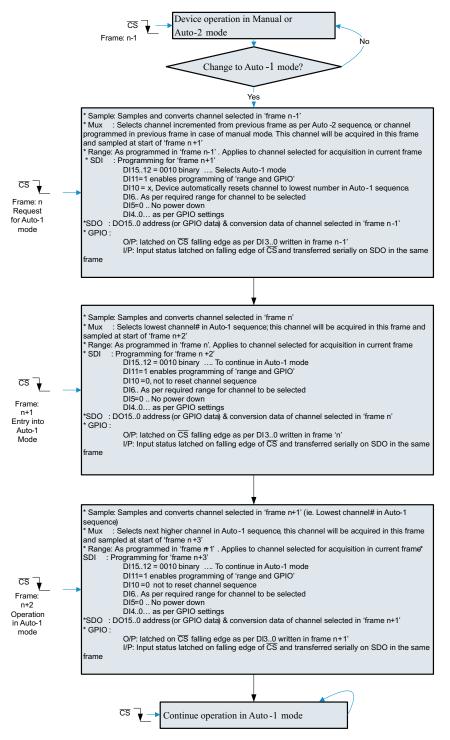
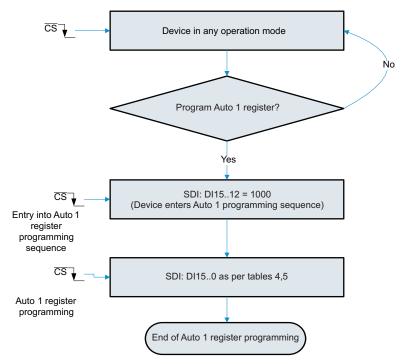


Figure 49. Entering and Running in Auto-1 Channel Sequencing Mode

	DEOET			DESCRIPTION						
BITS	RESET STATE	LOGIC STATE	FUNCTION							
DI15-12	0001	0010	Selects Auto-1 Mode							
DI11	0	1	Enables programming of bits DI10-00.							
		0	Device retains values of	DI10-00 from previous fram	е.					
DI10	0	1	The channel counter is r	The channel counter is reset to the lowest programmed channel in the Auto-1 Program Register						
0			The channel counter incl	rements every conversion (N	lo reset)					
DI09-07	000	XXX	Do not care							
DI06	0	0	Selects 2.5V i/p range (F	Selects 2.5V i/p range (Range 1)						
		1	Selects 5V i/p range (Ra	nge 2)						
DI05	0	0	Device normal operation	(no powerdown)						
		1	Device powers down on	the 16th SCLK falling edge						
DI04	0	0	SDO outputs current char result on DO1100.	SDO outputs current channel address of the channel on DO1512 followed by 12-bit conversion result on DO1100.						
		1	GPIO3-GPIO0 data (both input and output) is mapped onto DO15-DO12 in the order shown below. Lower data bits DO11-DO00 represent 12-bit conversion result of the current channel.							
			DO15	DO14	DO13	DO12				
			GPIO3	GPIO2	GPIO1	GPIO0				
DI03-00	0000			d as output. Device will igno GPIO information is given be		el which is configured				
			DI03	DI02	DI01	DI00				
			GPIO3	GPIO2	GPIO1	GPIO0				

Table 2. Mode Control Register Settings for Auto-1 Mode

The Auto-1 Program Register is programmed (once on powerup or reset) to pre-select the channels for the Auto-1 sequence. Auto-1 Program Register programming requires two CS frames for complete programming. In the first CS frame the device enters the Auto-1 register programming sequence and in the second frame it programs the Auto-1 Program Register. Refer to Table 2, Table 3, and Table 4 for complete details.



NOTE: The device continues its operation in selected mode during programming. SDO is valid, however it is not possible to change the range or write GPIO data into the device during programming.

Figure 50. Auto-1 Register Programming Flowchart

BITS	RESET		DESCRIPTION						
ытэ	STATE	LOGIC STATE	FUNCTION						
FRAME 1									
DI15-12	NA	1000	Device enters Auto-1 program sequence. Device programming is done in the next frame.						
DI11-00	NA	Do not care							
FRAME 2									
DI15-00	All 1s	1 (individual bit)	A particular channel is programmed to be selected in the channel scanning sequence. The channel numbers are mapped one-to-one with respect to the SDI bits; e.g. DI15 \rightarrow Ch15, DI14 \rightarrow Ch14 DI00 \rightarrow Ch00						
0 (individual		0 (individual bit)	A particular channel is programmed to be skipped in the channel scanning sequence. The channel numbers are mapped one-to-one with respect to the SDI bits; e.g. DI15 \rightarrow Ch15, DI14 \rightarrow Ch14 DI00 \rightarrow Ch00						

Table 3. Program Register Settings for Auto-1 Mode

Table 4. Mapping of Channels to SDI Bits for 16,12,8,4 Channel Devices

Device ⁽¹⁾		SDI BITS														
	DI15	DI14	DI13	DI12	DI11	DI10	D109	DI08	DI07	DI06	DI05	DI04	DI03	DI02	DI01	D100
16 Chan	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0
12 Chan	Х	Х	Х	Х	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0
8 Chan	Х	Х	Х	Х	Х	Х	Х	Х	1/0	1/0	1/0	1/0	1/0	1/0	1/0	1/0
4 Chan	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	Х	1/0	1/0	1/0	1/0

(1) When operating in Auto-1 mode, the device only scans the channels programmed to be selected.

OPERATING IN AUTO-2 MODE

The details regarding entering and running in Auto-2 channel sequencing mode are illustrated in Figure 51. Table 5 lists the Mode Control Register settings for Auto-2 mode in detail.

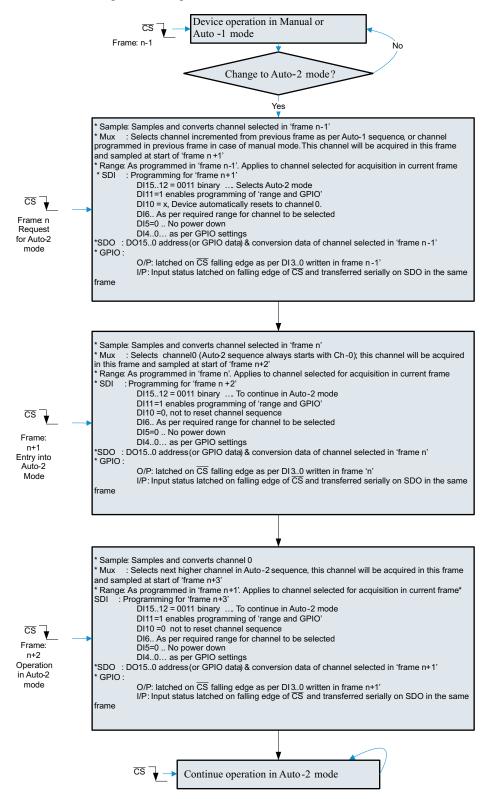
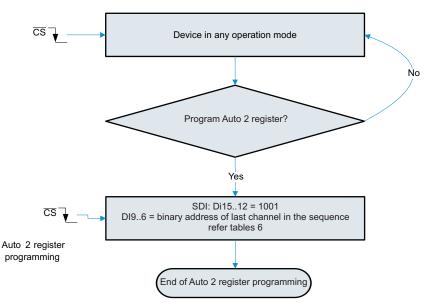


Figure 51. Entering and Running in Auto-2 Channel Sequencing Mode

	DEOET			DESCRIPTION						
BITS	RESET STATE	LOGIC STATE	FUNCTION							
DI15-12	0001	0011	Selects Auto-2 Mode							
DI11	0	1	Enables programming of	bits DI10-00.						
		0	Device retains values of	DI10-00 from the previous f	rame.					
DI10	0	1	Channel number is reset	to Ch-00.						
		0	Channel counter increme	ents every conversion.(No re	eset).					
DI09-07	000	ххх	Do not care							
DI06	0	0	Selects 2.5V i/p range (R	Selects 2.5V i/p range (Range 1)						
		1	Selects 5V i/p range (Range 2)							
DI05	0	0	Device normal operation	(no powerdown)						
		1	Device powers down on	the 16th SCLK falling edge						
DI04	0	0		SDO outputs the current channel address of the channel on DO1512 followed by the 12-bit conversion result on DO1100.						
		1		n input and output) is mappe D00 represent the 12-bit cor						
			DO15	DO14	DO13	DO12				
			GPIO3	GPIO2	GPIO1	GPIO0				
DI03-00	0000			d as output. Device ignores D information is given below		ich is configured as				
			DI03	DI02	DI01	DI00				
			GPIO3	GPIO2	GPIO1	GPIO0				

Table 5. Mode Control Register Settings for Auto-2 Mode

The Auto-2 Program Register is programmed (once on powerup or reset) to pre-select the last channel (or sequence depth) in the Auto-2 sequence. Unlike Auto-1 Program Register programming, Auto-2 Program Register programming requires only 1 CS frame for complete programming. See Figure 52 and Table 6 for complete details.



NOTE: The device continues its operation in the selected mode during programming. SDO is valid, however it is not possible to change the range or write GPIO data into the device during programming.

Figure 52. Auto-2 Register Programming Flowchart

Table 6. Program Register Settings for Auto-2 Mode

BITS RESET STATE		DESCRIPTION						
		LOGIC STATE	FUNCTION					
DI15-12	NA	1001	Auto-2 program register is selected for programming					
DI11-10	NA	Do not care						
DI09-06	NA	aaaa	This 4-bit data represents the address of the last channel in the scanning sequence. During device operation in Auto-2 mode, the channel counter starts at CH-00 and increments every frame until it equals "aaaa". The channel counter roles over to CH-00 in the next frame.					
DI05-00	NA	Do not care						

CONTINUED OPERATION IN A SELECTED MODE

Once a device is programmed to operate in one of the modes, the user may want to continue operating in the same mode. Mode Control Register settings to continue operating in a selected mode are detailed in Table 7.

	RESET	DESCRIPTION						
BITS	STATE	LOGIC STATE	FUNCTION					
DI15-12	0001	0000	The device continues to operate in the selected mode. In Auto-1 and Auto-2 modes the channel counter increments normally, whereas in the Manual mode it continues with the last selected channel. The device ignores data on DI11-DI00 and continues operating as per the previous settings. This feature is provided so that SDI can be held low when no changes are required in the Mode Control Register settings.					
DI11-00	All '0'	Device igno	Device ignores these bits when DI15-12 is set to 0000 logic state					

Table 7. Continued Operation in a Selected Mode

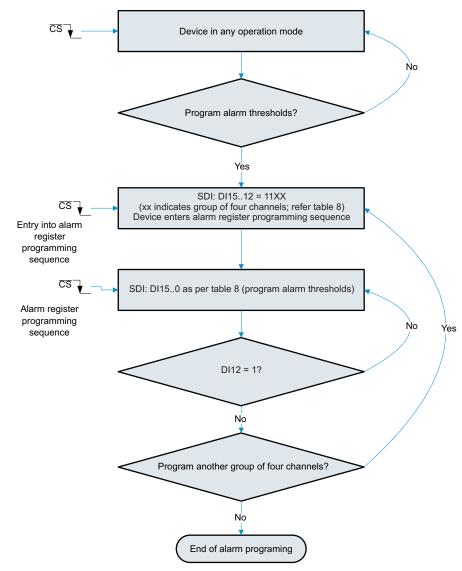
PROGRAMMING ALARM THRESHOLDS

There are two Alarm Program Registers per channel, one for setting the high alarm threshold and the other for setting the low alarm threshold. For ease of programming, two alarm programming registers per channel, corresponding to four consecutive channels, are assembled into one group (a total eight registers). There are four such groups for 16 channel devices and 3/2/1 such groups for 12/8/4 channel devices respectively. The grouping of the various channels for each device in the ADS79XX family is listed in Table 8. The details regarding programming the alarm thresholds are illustrated in the flowchart in Figure 53. Table 9 lists the details regarding the Alarm Program Register settings.

GROUP NO.	REGISTERS	APPLICABLE FOR DEVICE
0	High and low alarm for channel 0, 1, 2, and 3	ADS795350, ADS795754, ADS796158
1	High and low alarm for channel 4, 5, 6, and 7	ADS795351, ADS795755, ADS796159
2	High and low alarm for channel 8, 9, 10, and 11	ADS7953 and 52, ADS7957 and 56, ADS7961 and 60
3	High and low alarm for channel 12, 13, 14, and 15	ADS7953, ADS7957, ADS7961

Table 8. Grouping of Alarm Program Registers

Each alarm group requires 9 \overline{CS} frames for programming their respective alarm thresholds. In the first frame the device enters the programming sequence and in each subsequent frame it programs one of the registers from the group. The device offers a feature to program less than eight registers in one programming sequence. The device exits the alarm threshold programming sequence in the next frame after it encounters the first 'Exit Alarm Program' bit high.



NOTE: The device continues its operation in selected mode during programming. SDO is valid, however it is not possible to change the range or write GPIO data into the device during programming.

Figure 53. Alarm Program Register Programming Flowchart

	BITS RESET STATE LO		DESCRIPTION						
BITS			FUNCTION						
FRAME 1	1								
DI15-12	NA	1100	Device enters 'alarm programming sequence' for group 0						
			Device enters 'alarm programming sequence' for group 1						
1110			Device enters 'alarm programming sequence' for group 2						
		1111	Device enters 'alarm programming sequence' for group 3						
Note: DI1 format.	5-12 = 11bb is the a	larm progra	mming request for group bb. Here 'bb' represents the alarm programming group number in binary						
DI11-14	NA	Do not ca	re						
FRAME 2	2 AND ONWARDS	1							

Table 9. Alarm Program Register Settings

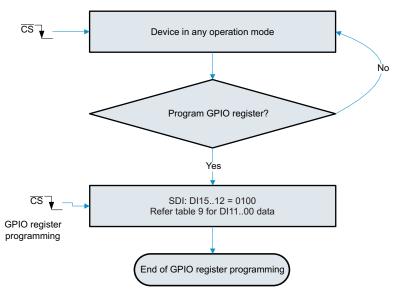
			DESCRIPTION					
BITS RESET STATE		LOGIC STATE	FUNCTION					
DI15-14	15-14 NA cc		Where "cc" represents the lower two bits of the channel number in binary format. The device programs the alarm for the channel represented by the binary number "bbcc". Note that "bb" is programmed in the first frame.					
DI13	NA	1	High alarm register selection					
			Low alarm register selection					
DI12	NA	0	Continue alarm programming sequence in next frame					
1		1	Exit Alarm Programming in the next frame. Note: If the alarm programming sequence is not terminated using this feature then the device will remain in the alarm programming sequence state and all SDI data will be treated as alarm thresholds.					
DI11-10	NA	хх	Do not care					
DI09-00	All ones for high alarm register and all zeros for low alarm register	word of th	t data represents the alarm threshold. The 10-bit alarm threshold is compared with the upper 10-bit e 12-bit conversion result. The device sets off an alarm when the conversion result is higher (High lower (Low Alarm) than this number.					

Table 9. Alarm Program Register Settings (continued)

PROGRAMMING GPIO REGISTERS

The device has four General Purpose Input and Output (GPIO) pins. Each of the four pins can be independently programmed as General Purpose Output (GPO) or General Purpose Input (GPI). It is also possible to use the GPIOs for some pre-assigned functions (refer to Table 10 for details). GPO data can be written into the device through the SDI line. The device refreshes the GPO data on every \overline{CS} falling edge as per the SDI data written in the previous frame. Similarly, the device latches GPI status on the \overline{CS} falling edge and outputs it on SDO (if GPI is read enabled by writing DI04 = 1 during the previous frame) in the same frame starting on the \overline{CS} falling edge.

The details regarding programming the GPIO registers are illustrated in the flowchart in Figure 54. Table 10 lists the details regarding GPIO Register programming settings.



NOTE: The device continues its operation in selected mode during programming. SDO is valid, however it is not possible to change the range or write GPIO data into the device during programming.

Figure 54. GPIO Program Register Programming Flowchart

Table 10. GPIO Program Register Settings

	RESET		DESCRIPTION					
BITS	STATE	LOGIC STATE	FUNCTION					
DI15-12	NA	0100	Device selects GPIO Program Registers for programming.					
DI11-10	00	00	Do not program these bits to any logic state other than '00'					
D109	DI09 0		Device resets all registers in the next \overline{CS} frame to the reset state shown in the corresponding tables (it also resets itself).					
		0	Device normal operation					
DI08	0	1	Device configures GPIO3 as the device power-down input.					
		0	GPIO3 remains general purpose I or O					
DI07	0	1	Device configures GPIO2 as device range input.					
0			GPIO2 remains general purpose I or O					
DI06-04	000	000	GPIO1 and GPIO0 remain general purpose I or O					
		xx1	Device configures GPIO0 as 'high or low' alarm output. This is an active high output. GPIO1 remains general purpose I or O.					
		010	Device configures GPIO0 as high alarm output. This is an active high output. GPIO1 remains general purpose I or O.					
		100	Device configures GPIO1 as low alarm output. This is an active high output. GPIO0 remains general purpose I or O.					
		110	Device configures GPIO1 as low alarm output and GPIO0 as a high alarm output. These are active high outputs.					
Note: The	e following s	ettings are	valid for GPIO which are not assigned a specific function through bits DI0804					
DI03	0	1	GPIO3 pin is configured as general purpose output					
		0	GPIO3 pin is configured as general purpose input					
DI02	0	1	GPIO2 pin is configured as general purpose output					
		0	GPIO2 pin is configured as general purpose input					
DI01	0	1	GPIO1 pin is configured as general purpose output					
		0	GPIO1 pin is configured as general purpose input					
DI00	0	1	GPIO0 pin is configured as general purpose output					
		0	GPIO0 pin is configured as general purpose input					

APPLICATION INFORMATION

ANALOG INPUT

The ADS79XX device family offers 12/10/8-bit ADCSs with 16/12/8/4 channel multiplexers for analog input. The multiplexer output is available on the MXO pin. AINP is the ADC input pin. The devices offers flexibility for a system designer as both signals are accessible esternally.

Typically it is convenient to short MXO to the AINP pin so that signal input to each multiplexer channel can be processed independently. In this condition it is recommended to limit source impedance to 50Ω or less. Higher source impedance may affect the signal settling time after a multiplexer channel change. This condition can affect linearity and total harmonic distortion.

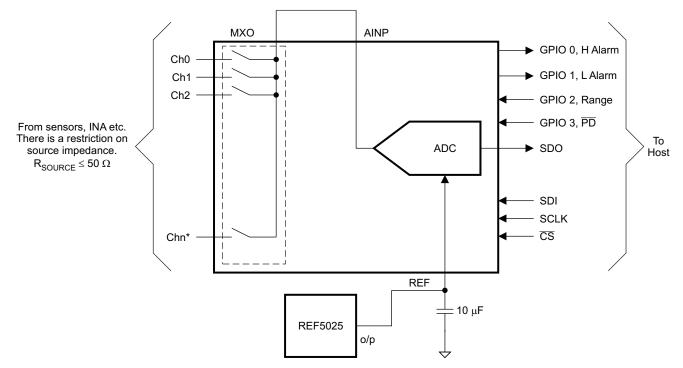


Figure 55. Typical Application Diagram Showing MXO Shorted to AINP

Another option is to add a common ADC driver buffer between the MXO and AINP pins. This relaxes the restriction on source impedance to a large extent. Refer to the typical characteristics section for the effect of source impedance on device performance. The typical characteristics show that the device has respectable performance with up to $1k\Omega$ source impedance. This topology (including a common ADC driver) is useful when all channel signals are within the acceptable range of the ADC. In this case the user can save on signal conditioning circuit for each channel.

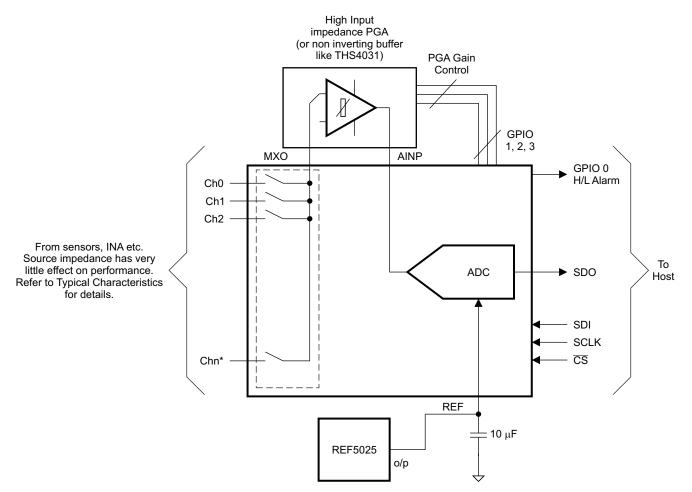


Figure 56. Typical Application Diagram Showing Common Buffer/PGA for all Channels

When the converter samples an input, the voltage difference between AINP and AGND is captured on the internal capacitor array. The (peak) input current through the analog inputs depends upon a number of factors: sample rate, input voltage, and source impedance. The current into the ADS79XX charges the internal capacitor array during the sample period. After this capacitance has been fully charged, there is no further input current. When the converter goes into hold mode, the input impedance is greater than 1 G Ω .

Care must be taken regarding the absolute analog input voltage. To maintain linearity of the converter, the Ch0 ... Chn and AINP inputs should be within the limits specified. Outside of these ranges, converter linearity may not meet specifications.

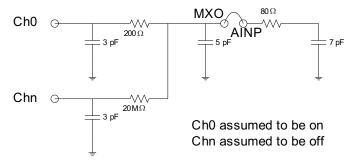


Figure 57. ADC and Mux Equivalent Circuit

REFERENCE

The ADS79XX can operate with an external 2.5V \pm 10mV reference. A clean, low noise, well-decoupled reference voltage on the REF pin is required to ensure good performance of the converter. A low noise band-gap reference like the REF5025 can be used to drive this pin. A 10- μ F ceramic decoupling capacitor is required between the REF and GND pins of the converter. The capacitor should be placed as close as possible to the pins of the device.

POWER SAVING

The ADS79XX devices offer a power-down feature to save power when not in use. There are two ways to powerdown the device. It can be powered down by writing DI05 = 1 in the Mode Control register (refer to Table 1, Table 2 and Table 5); in this case the device powers down on the 16th falling edge of SCLK in the next data frame. Another way to powerdown the device is through GPIO. GPIO3 can act as a PD input (refer to Table 10, for assigning this functionality to GPIO3). This is an asynchronous and active low input. The device powers down instantaneously after GPIO3 (PD) = 0. The device will powerup again on the CS falling edge while DI05 = 0 in the Mode Control register and GPIO3 (PD) = 1.

DIGITAL OUTPUT

As discussed previously in the Device Operation section, the digital output of the ADS79XX devices is SPI compatible. The following table lists the output codes corresponding to various analog input voltages.

DESCRIPTION	ANALOG VALUE		DIGITAL OUT	PUT
Full scale range	Range 1 \rightarrow V _{ref}	Range $2 \rightarrow 2 \times V_{ref}$	STRAIGHT BI	NARY
Least significant bit (LSB)	V _{ref} /4096	2V _{ref} /4096	BINARY CODE	HEX CODE
Full scale	V _{ref} – 1 LSB	2V _{ref} – 1 LSB	1111 1111 1111	FFF
Midscale	V _{ref} /2	V _{ref}	1000 0000 0000	800
Midscale – 1 LSB	V _{ref} /2 – 1 LSB	V _{ref} – 1 LSB	0111 1111 1111	7FF
Zero	0 V	0 V	0000 0000 0000	000

Table 11. Ideal Input Voltages and Output Codes for 12-Bit Devices (ADS7950/51/52/53)

Table 12. Ideal Input Voltages and Output Codes for 10-Bit Devices (ADS7954/55/56/57)

DESCRIPTION		ANALOG VALUE	DIGITAL OUT	PUT
Full scale range	Range 1 \rightarrow V _{ref}	Range $2 \rightarrow 2 \times V_{ref}$	STRAIGHT BI	NARY
Least significant bit (LSB)	V _{ref} /1024	2V _{ref} /1024	BINARY CODE	HEX CODE
Full scale	V _{ref} – 1 LSB	2V _{ref} – 1 LSB	11 1111 1111	3FF
Midscale	V _{ref} /2	V _{ref}	10 0000 0000	200
Midscale – 1 LSB	V _{ref} /2 – 1 LSB	V _{ref} – 1 LSB	01 1111 1111	1FF
Zero	0 V	0 V	00 0000 0000	000

DESCRIPTION		ANALOG VALUE	DIGITAL OUT	PUT
Full scale range	Range 1 \rightarrow V _{ref}	Range $2 \rightarrow 2 \times V_{ref}$	STRAIGHT BI	NARY
Least significant bit (LSB)	V _{ref} /256	2V _{ref} /256	BINARY CODE	HEX CODE
Full scale	V _{ref} – 1 LSB	2V _{ref} – 1 LSB	1111 1111	FF
Midscale	V _{ref} /2	V _{ref}	1000 0000	80
Midscale – 1 LSB	V _{ref} /2 – 1 LSB	V _{ref} – 1 LSB	0111 1111	7F
Zero	0 V	0 V	0000 0000	00

PACKAGE OPTION ADDENDUM

11-Jul-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
ADS7950SBDBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7950SBDBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7950SBDBTR	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7950SBDBTRG4	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7950SDBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7950SDBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7950SDBTR	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7950SDBTRG4	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7951SBDBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7951SBDBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7951SBDBTR	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7951SBDBTRG4	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7951SDBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7951SDBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7951SDBTR	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7951SDBTRG4	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7952SBDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7952SBDBTG4	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7952SBDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7952SBDBTRG4	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7952SDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7952SDBTG4	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7952SDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7952SDBTRG4	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7953SBDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

PACKAGE OPTION ADDENDUM

11-Jul-2008

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³
ADS7953SBDBTG4	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7953SBDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7953SBDBTRG4	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7953SDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7953SDBTG4	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7953SDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7953SDBTRG4	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7954SDBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7954SDBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7954SDBTR	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7954SDBTRG4	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7955SDBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEA
ADS7955SDBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEA
ADS7955SDBTR	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7955SDBTRG4	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEA
ADS7956SDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEA
ADS7956SDBTG4	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7956SDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7956SDBTRG4	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEA
ADS7957SDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7957SDBTG4	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7957SDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEA
ADS7957SDBTRG4	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEA
ADS7958SDBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAI
ADS7958SDBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEA
ADS7958SDBTR	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS &	CU NIPDAU	Level-2-260C-1 YEA

11-Jul-2008

				Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
ADS7958SDBTRG4	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7959SDBT	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7959SDBTG4	ACTIVE	TSSOP	DBT	30	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7959SDBTR	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7959SDBTRG4	ACTIVE	TSSOP	DBT	30	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7960SDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7960SDBTG4	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7960SDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7960SDBTRG4	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7961SDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7961SDBTG4	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
ADS7961SDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF
ADS7961SDBTRG4	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAF

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

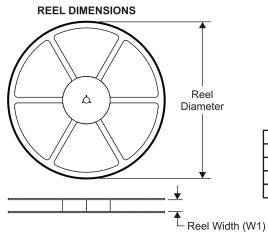
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

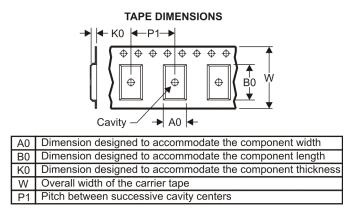
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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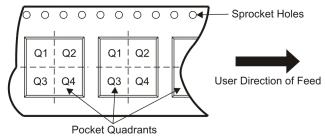
1-Jul-2008

TAPE AND REEL INFORMATION





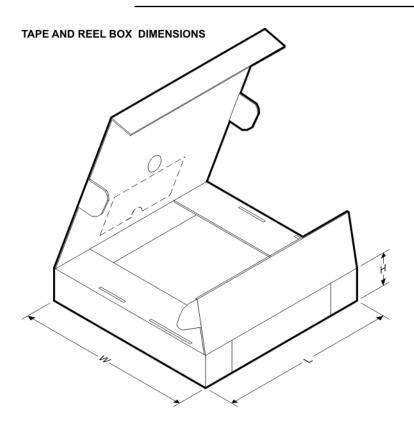
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS7950SBDBTR	TSSOP	DBT	30	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7950SDBTR	TSSOP	DBT	30	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7951SBDBTR	TSSOP	DBT	30	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7951SDBTR	TSSOP	DBT	30	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7952SBDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
ADS7952SDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
ADS7953SBDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
ADS7953SDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
ADS7954SDBTR	TSSOP	DBT	30	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7955SDBTR	TSSOP	DBT	30	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7956SDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7957SDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7958SDBTR	TSSOP	DBT	30	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7959SDBTR	TSSOP	DBT	30	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7960SDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
ADS7961SDBTR	TSSOP	DBT	38	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

1-Jul-2008



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ADS7950SBDBTR	TSSOP	DBT	30	2000	346.0	346.0	33.0	
ADS7950SDBTR	TSSOP	DBT	30	2000	346.0	346.0	33.0	
ADS7951SBDBTR	TSSOP	DBT	30	2000	346.0	346.0	33.0	
ADS7951SDBTR	TSSOP	DBT	30	2000	346.0	346.0	33.0	
ADS7952SBDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0	
ADS7952SDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0	
ADS7953SBDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0	
ADS7953SDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0	
ADS7954SDBTR	TSSOP	DBT	30	2000	346.0	346.0	33.0	
ADS7955SDBTR	TSSOP	DBT	30	2000	346.0	346.0	33.0	
ADS7956SDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0	
ADS7957SDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0	
ADS7958SDBTR	TSSOP	DBT	30	2000	346.0	346.0	33.0	
ADS7959SDBTR	TSSOP	DBT	30	2000	346.0	346.0	33.0	
ADS7960SDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0	
ADS7961SDBTR	TSSOP	DBT	38	2000	346.0	346.0	33.0	